

Single-Channel Proximity Detector

Features:

- Capacitive Proximity Detection System:
 - High Signal to Noise Ratio (SNR)
 - Adjustable sensitivity
 - Noise rejection filters
 - Automatic Environmental Compensation
 - Wide range of sensor shape and size support
 - Stuck Release Mechanism
- No External Components
- Low-Power mode
- Response Time Down to 75 ms
- Wide Operative Voltage:
 - 2.0V to 5.5V
- Operating Temperature:
 - -40°C to +85°C

Applications:

- Light Switch
- Portable Device Enabler
- White Goods and Appliances
- Office Equipment and Toys
- Display and Keypad Backlighting Activation
- SAR Compliant Application

Package Type

The device is available in 6-lead SOT-23 packaging (see [Figure 1](#)).

FIGURE 1: 6-PIN DIAGRAM

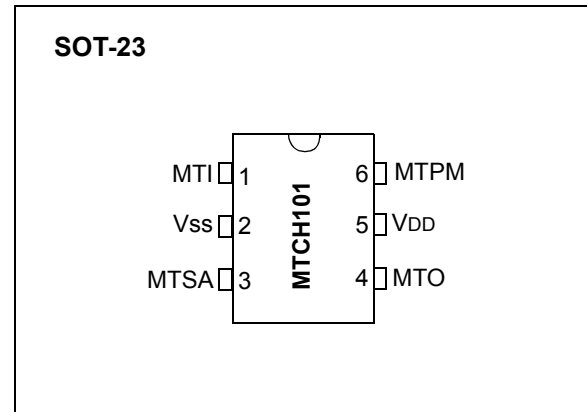


TABLE 1: 6-PIN SOT-23 PINOUT DESCRIPTION

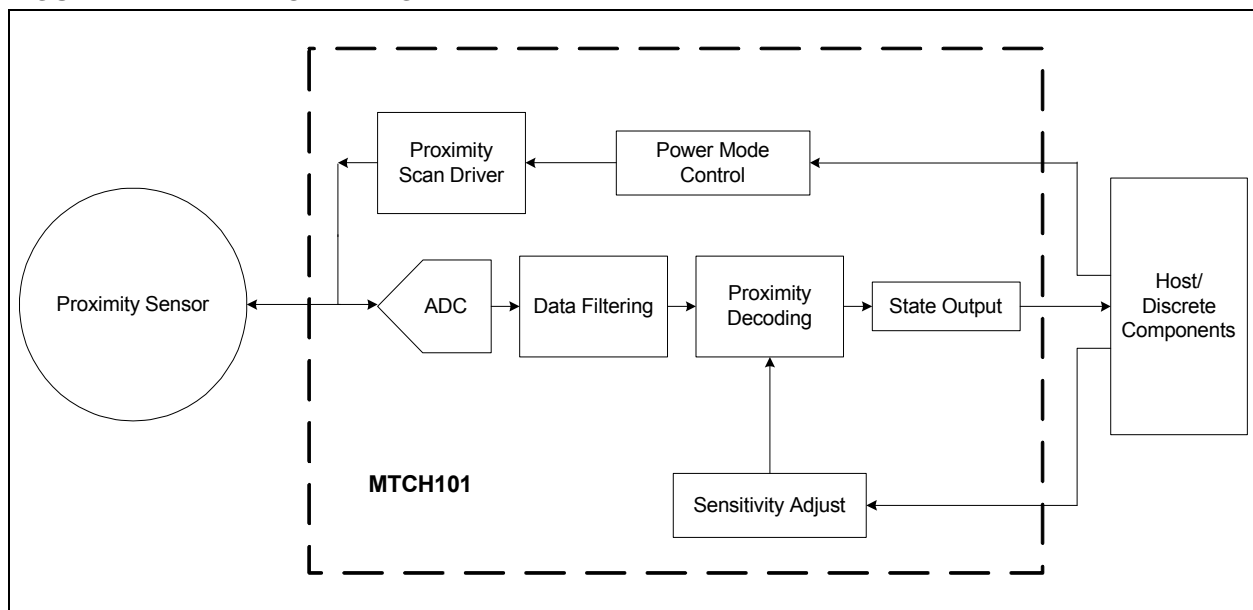
I/O	6-Pin SOT-23	Description
MTI	1	Proximity Sensor Input
Vss	2	Ground
MTSA	3	Sensitivity Adjust Input
MTO	4	Detect Output (Active-Low)
VDD	5	Power Supply Input
MTPM	6	Low-Power mode Select (Active-Low)

1.0 DEVICE OVERVIEW

The MTCH101 provides an easy way to add proximity or touch detection to any human interface application.

The device integrates a single-channel capacitive proximity detection, which can work through plastic, glass or wood-front panel. It also supports a wide range of conductive materials as sensor, like copper pad on PCB, silver or carbon printing on plastic, Indium Tin Oxide (ITO) pad, wire/cable, etc. On-board adjustable sensitivity and power mode selection allow the user to configure the device at run time easily. An active-low output will communicate the state of the sensor to a host/master MCU, or drive an indication LED (see [Figure 1-1](#)).

FIGURE 1-1: BLOCK DIAGRAM



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2.0 TYPICAL CIRCUIT

The MTCH101 can work either as a stand-alone device to control a LED (see [Figure 2-1](#)) to indicate touch/proximity, or work with host MCU (see [Figure 2-2](#)).

FIGURE 2-1: TYPICAL CIRCUIT AS STAND-ALONE

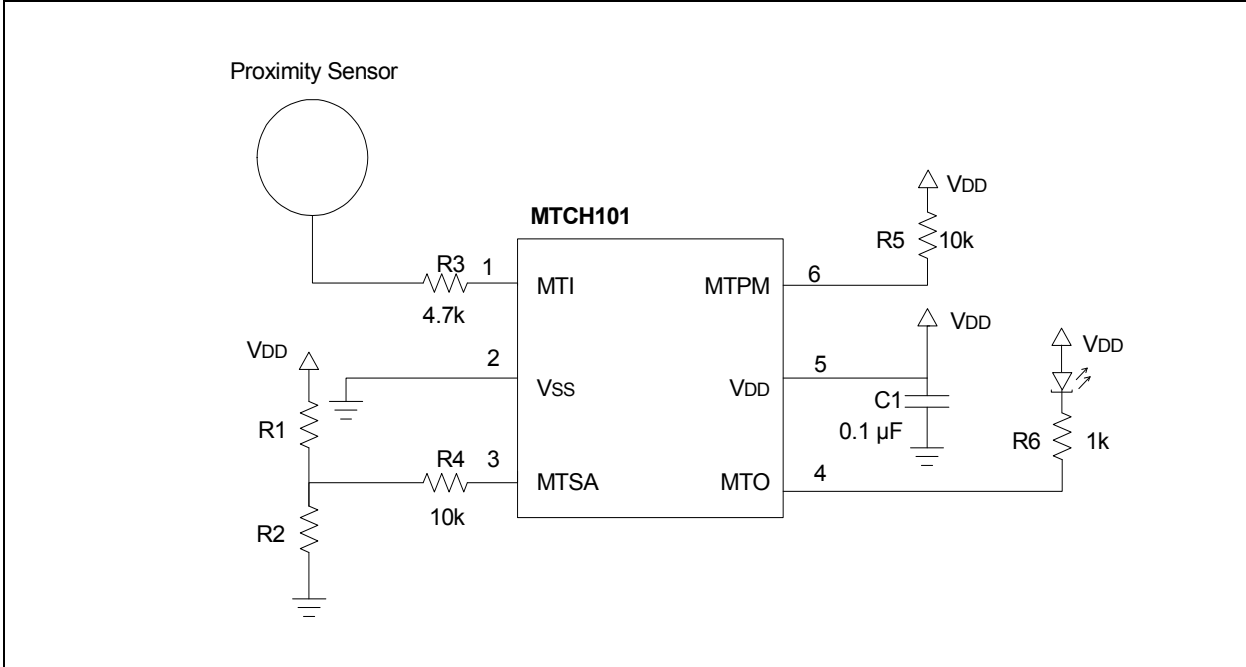
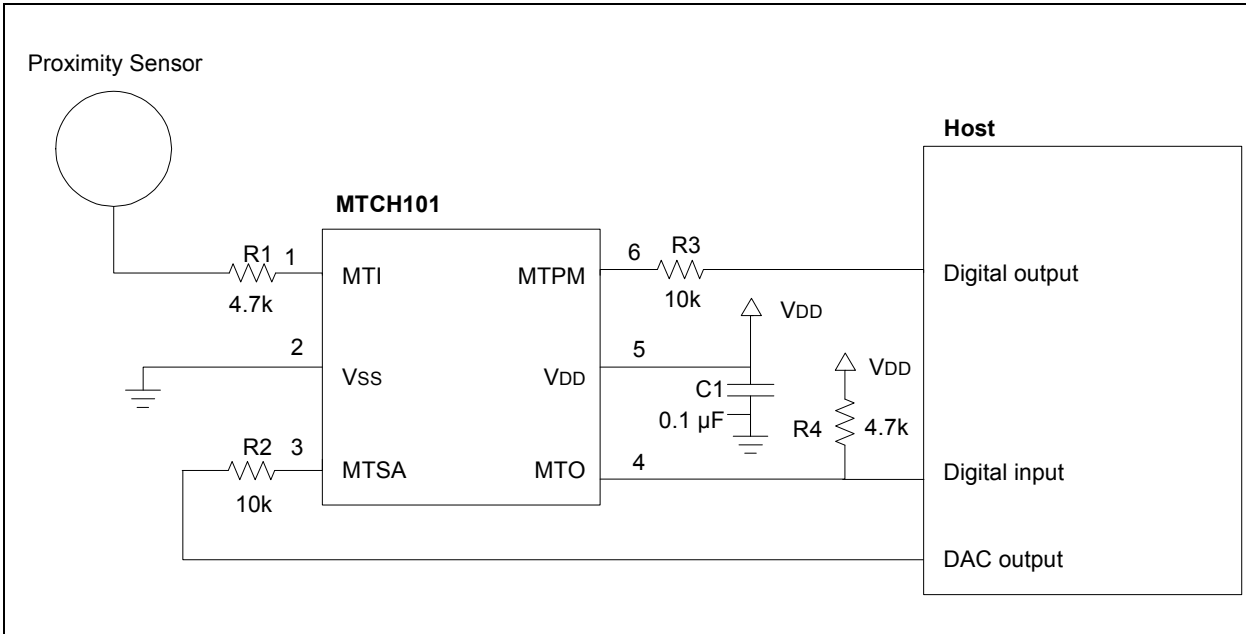


FIGURE 2-2: TYPICAL CIRCUIT WITH HOST MCU



3.0 SENSITIVITY ADJUSTMENT

The sensitivity of the system determines how far and fast it can respond to proximity or touch. The MTCH101 provides the MTSA pin to adjust the sensitivity, and the voltage on this pin will determine the sensitivity. VDD voltage will give the lowest sensitivity, while GND voltage will give the highest sensitivity.

The device will sample the voltage on the MTSA pin after each scan, so it does not only support setting a fixed sensitivity by a resistor ladder, but it also allows adjusting the sensitivity dynamically, while the device is running. A Digital-to-Analog Converter (DAC) controlled by the host, or a hardware potentiometer can be used to adjust the sensitivity. See typical circuit in [Figure 3-1](#) to [Figure 3-4](#).

FIGURE 3-1: FIXED SENSITIVITY USING RESISTOR LADDER

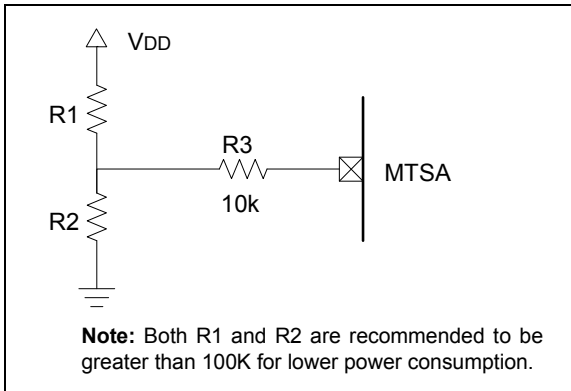


FIGURE 3-2: HARDWARE SENSITIVITY ADJUST USING POTENTIOMETER

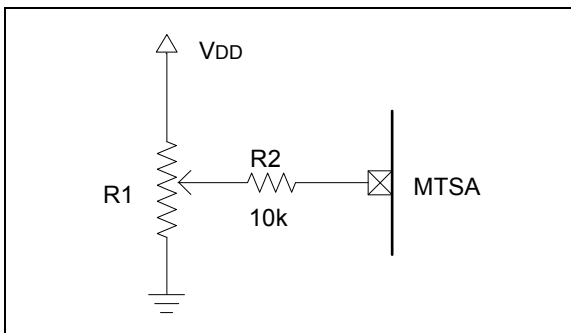


FIGURE 3-3: SENSITIVITY CONTROLLED BY HOST USING DAC

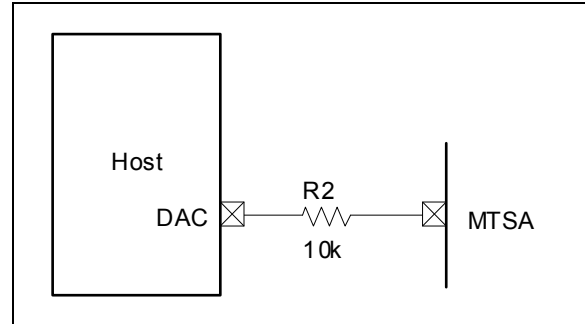
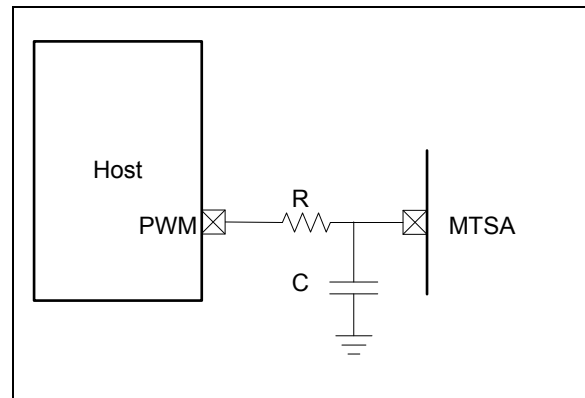


FIGURE 3-4: SENSITIVITY CONTROLLED BY HOST USING PWM



Note 1: Application Note AN538, "Using PWM to Generate Analog Output" has details about how to choose appropriate R and C values.

MTCH101

8.0 ELECTRICAL CHARACTERISTICS

8.1 Absolute Maximum Ratings^(†)

Ambient temperature under bias	-40°C to +125°C
Storage temperature	-65°C to +150°C
Voltage on pins with respect to V _{SS}	
on V _{DD} pin	0 to +6.5V
on all other pins	-0.3V to (V _{DD} + 0.3V)
Max. current	
out of V _{SS} pin	80 mA
into V _{DD} pin	80 mA
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{DD})	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{DD})	±20 mA
Max. output current	
sunk by any I/O pin	25 mA
sourced by any I/O pin	25 mA

[†]NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

8.2 Standard Operating Conditions

The standard operating conditions for any device are defined as:

Operating Voltage: $V_{DDMIN} \leq V_{DD} \leq V_{DDMAX}$

Operating Temperature: $T_{A_MIN} \leq T_A \leq T_{A_MAX}$

V_{DD} — Operating Supply Voltage⁽¹⁾

V_{DDMIN} +2.0V

V_{DDMAX} +5.5V

T_A — Operating Ambient Temperature Range

Industrial Temperature

T_{A_MIN} -40°C

T_{A_MAX} +85°C

Note 1: See Parameter D001 in Table 8-1.

Note: The tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

8.3 DC Characteristics

TABLE 8-1: MTCH101 (INDUSTRIAL)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified)				
Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
D001	VDD	Supply Voltage	2.0	—	5.5	V	
D002	VPOR	VDD Start Voltage to ensure Power-on-Reset	—	Vss	—	V	
D003	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	—	—	V/ms	

* These parameters are characterized but not tested.

† Data in “Typ” column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

TABLE 8-2: RESPONSE TIME AND CURRENT CONSUMPTION

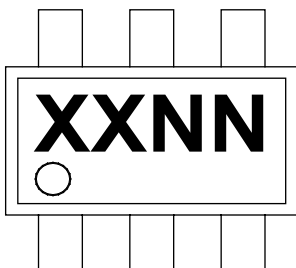
Power Mode	Typical Current (µA)	Highest Sensitivity Response Time (ms)		Lowest Sensitivity Response Time (ms)		Conditions
		Typical	Max.	Typical	Max.	
Normal mode	120	100	150	210	260	VDD = 2.0V
Low-Power mode	30	790	890	900	1000	
Normal mode	200	80	130	190	240	VDD = 3.3V
Low-Power mode	54	640	740	750	850	
Normal mode	340	76	119	190	220	VDD = 5.0V
Low-Power mode	97	530	620	640	730	

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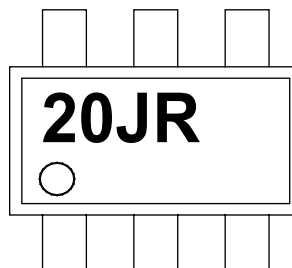
9.0 PACKAGING INFORMATION

9.1 Package Marking Information

6-Lead SOT-23



Example



Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.	

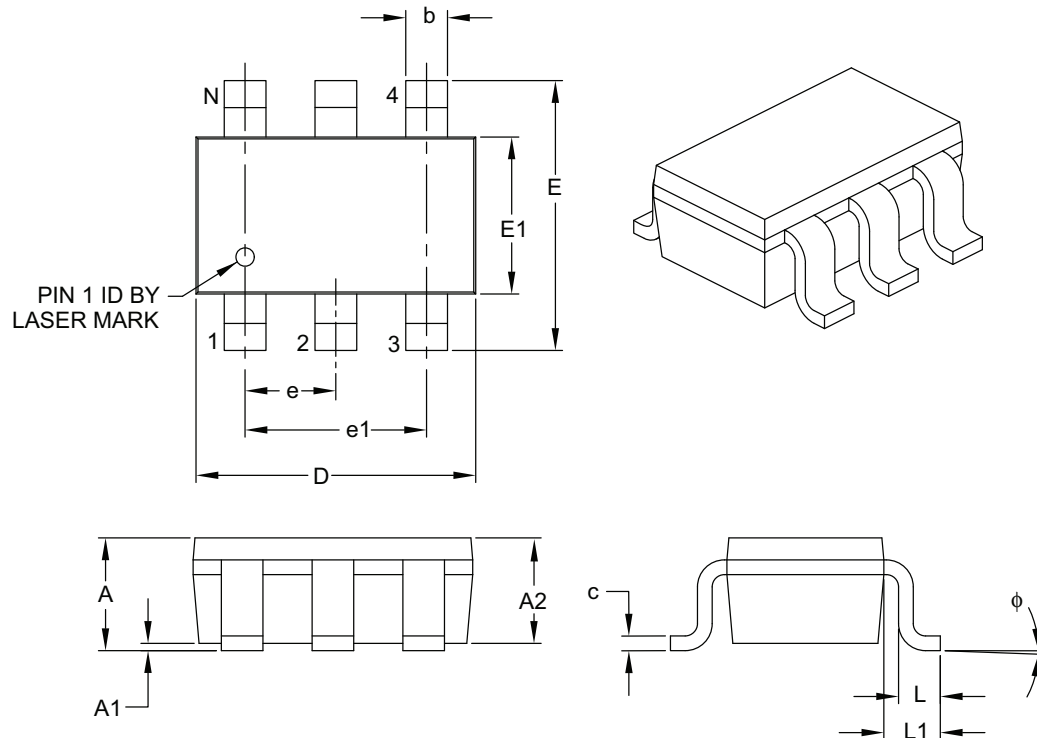
- * Standard PIC[®] device marking consists of Microchip part number, year code, week code, and traceability code. For PIC device marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

9.2 Package Details

The following sections give the technical details of the packages.

6-Lead Plastic Small Outline Transistor (OT) [SOT-23]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	6		
Pitch	e	0.95 BSC		
Outside Lead Pitch	e1	1.90 BSC		
Overall Height	A	0.90	–	1.45
Molded Package Thickness	A2	0.89	–	1.30
Standoff	A1	0.00	–	0.15
Overall Width	E	2.20	–	3.20
Molded Package Width	E1	1.30	–	1.80
Overall Length	D	2.70	–	3.10
Foot Length	L	0.10	–	0.60
Footprint	L1	0.35	–	0.80
Foot Angle	ϕ	0°	–	30°
Lead Thickness	c	0.08	–	0.26
Lead Width	b	0.20	–	0.51

Notes:

- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.127 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

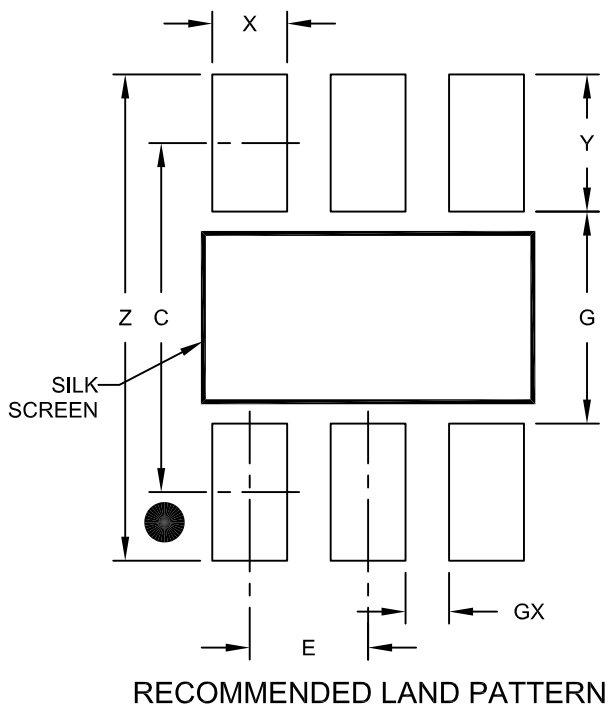
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-028B

MTCH101

6-Lead Plastic Small Outline Transistor (OT) [SOT-23]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.95 BSC		
Contact Pad Spacing	C		2.80	
Contact Pad Width (X6)	X			0.60
Contact Pad Length (X6)	Y			1.10
Distance Between Pads	G	1.70		
Distance Between Pads	GX	0.35		
Overall Width	Z			3.90

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2028A